Vishay Siliconix

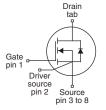
HALOGEN

FREE

E Series Power MOSFET

PowerPAK® 10 x 12





N-Channel MOSFET

PRODUCT SUMMARY					
V _{DS} (V) at T _J max.	65	50			
R _{DS(on)} typ. (Ω) at 25 °C	V _{GS} = 10 V	0.070			
Q _g max. (nC)	6	2			
Q _{gs} (nC)	1	7			
Q _{gd} (nC)	(9			
Configuration	Sin	Single			

FEATURES

- 4th generation E series technology
- Low figure-of-merit (FOM) Ron x Qg
- Low effective capacitance (Co(er))
- · Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- · Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	PowerPAK 10 x 12
Lead (Pb)-free and halogen-free	SiHK075N60E-T1-GE3

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
PARAMETER		SYMBOL	LIMIT	UNIT		
Drain-source voltage			V_{DS}	600	V	
Gate-source voltage			V_{GS}	± 30		
Continuous drain current (T _J = 150 °C)	V _{GS} at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$	- I _D	29	А	
	VGS at 10 V	T _C = 100 °C		18		
Pulsed drain current ^a			I _{DM}	75	I	
Linear derating factor				1.33	W/°C	
Single pulse avalanche energy b			E _{AS}	204	mJ	
Maximum power dissipation			P_{D}	167	W	
Operating junction and storage temperature ran	ge		T _J , T _{stg}	-55 to +150	°C	
Drain-source voltage slope $T_J = 125 ^{\circ}\text{C}$		dv/dt	100	V/ns		
Reverse diode dv/dt ^d			23	V/IIS		

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 120 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 3.8 A
- c. 1.6 mm from case
- d. $I_{SD} \le I_D$, di/dt = 100 A/ μ s, starting T_J = 25 °C



Vishay Siliconix

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	R _{thJA}	=	50 ^c	°C/W	
Maximum junction-to-case (drain)	R _{thJC}	-	0.75	C/VV	

PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT	
Static							l
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		600	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference to 25 °C, I _D = 1 mA		-	0.64	-	V/°C
Gate-source threshold voltage (N)	V _{GS(th)}	V _{DS} =	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$		-	5.0	V
Osta saura laskasa		V _{GS} = ± 20 V		-	-	± 100	nA
Gate-source leakage	I_{GSS}	,	$V_{GS} = \pm 30 \text{ V}$		-	± 1	μΑ
7		V _{DS} =	600 V, V _{GS} = 0 V	-	-	1	
Zero gate voltage drain current	I _{DSS}	$V_{DS} = 480 \text{ V}$	$^{\circ}$, $V_{GS} = 0 \text{ V}$, $T_{J} = 125 ^{\circ}\text{C}$	-	-	10	μA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 13 A	-	0.070	0.080	Ω
Forward transconductance ^a	9 _{fs}	V _{DS}	V _{DS} = 10 V, I _D = 13 A		2.3	-	S
Dynamic							
Input capacitance	C_{iss}		$V_{GS} = 0 \text{ V},$ $V_{DS} = 100 \text{ V},$		2582	-	pF
Output capacitance	C _{oss}	,			99	-	
Reverse transfer capacitance	C_{rss}	f = 1 MHz		-	5	-	
Effective output capacitance, energy related ^a	$C_{o(er)}$	V_{DS} = 0 V to 480 V, V_{GS} = 0 V		-	75	-	
Effective output capacitance, time related ^b	C _{o(tr)}			-	474	-	
Total gate charge	Qg		V _{GS} = 10 V I _D = 13 A, V _{DS} = 480 V		41	62	nC
Gate-source charge	Q_{gs}	$V_{GS} = 10 \text{ V}$			17	-	
Gate-drain charge	Q_gd			-	9	-	1
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 480 \text{ V}, I_{D} = 13 \text{ A}, V_{GS} = 10 \text{ V}, R_{g} = 9.1 \Omega$		-	26	52	- ns
Rise time	t _r			-	26	52	
Turn-off delay time	$t_{d(off)}$			-	45	90	
Fall time	t _f			-	12	24	
Gate input resistance	R_{g}	f = 1 MHz		0.4	0.8	1.6	Ω
Drain-Source Body Diode Characteristic	cs						
Continuous source-drain diode current	Is	MOSFET symbol showing the integral reverse p - n junction diode		-	-	29	
Pulsed diode forward current	I _{SM}			-	-	75	A
Diode forward voltage	V _{SD}	T _J = 25 °C, I _S = 13 A, V _{GS} = 0 V		-	-	1.2	V
Reverse recovery time	t _{rr}	$T_J = 25 ^{\circ}\text{C}, I_F = I_S = 13 \text{A},$ $di/dt = 100 \text{A/}\mu\text{s}, V_R = 25 \text{V}$		-	317	816	ns
Reverse recovery charge	Q _{rr}			-	4.2	12.8	μC
Reverse recovery current	I _{RRM}			-	23	-	Α

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}
- b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}
- c. When mounted on 1" x 1" FR4 board



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

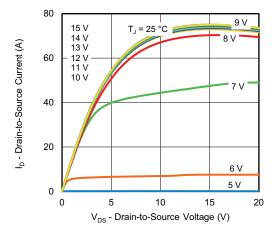


Fig. 1 - Typical Output Characteristics

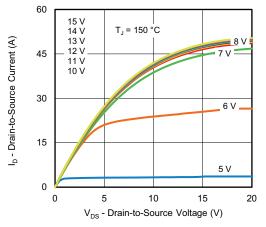


Fig. 2 - Typical Output Characteristics

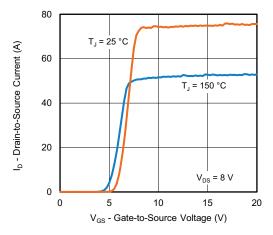


Fig. 3 - Typical Transfer Characteristics

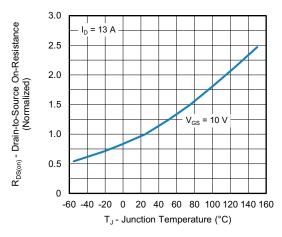


Fig. 4 - Normalized On-Resistance vs. Temperature

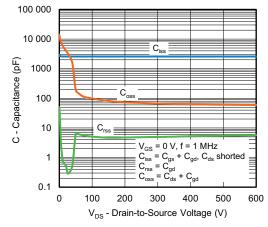


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

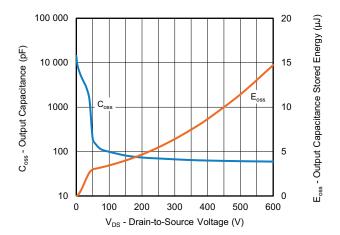


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}



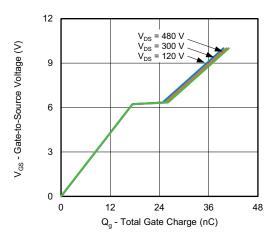


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

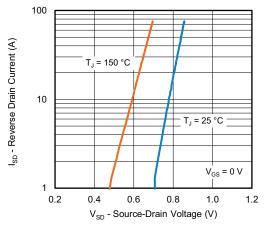


Fig. 8 - Typical Source-Drain Diode Forward Voltage

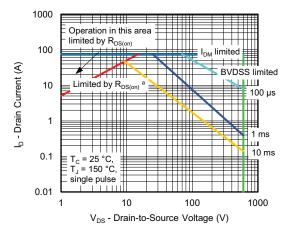


Fig. 9 - Maximum Safe Operating Area



a. $V_{GS} > minimum \ V_{GS}$ at which $R_{DS(on)}$ is specified

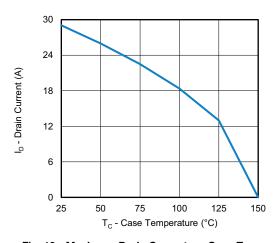


Fig. 10 - Maximum Drain Current vs. Case Temperature

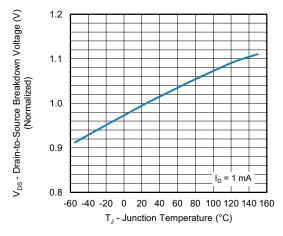


Fig. 11 - Temperature vs. Drain-to-Source Voltage



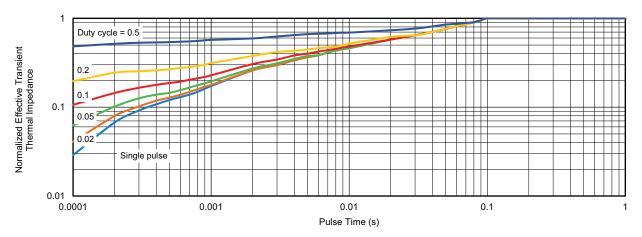


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

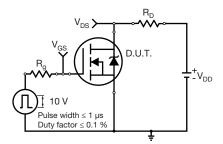


Fig. 13 - Switching Time Test Circuit

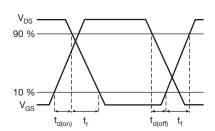


Fig. 14 - Switching Time Waveforms

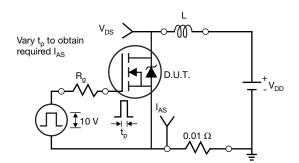


Fig. 15 - Unclamped Inductive Test Circuit

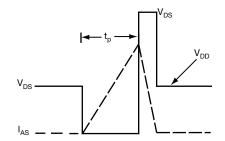


Fig. 16 - Unclamped Inductive Waveforms

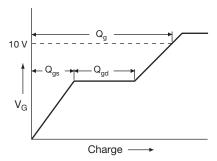


Fig. 17 - Basic Gate Charge Waveform

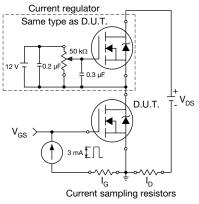
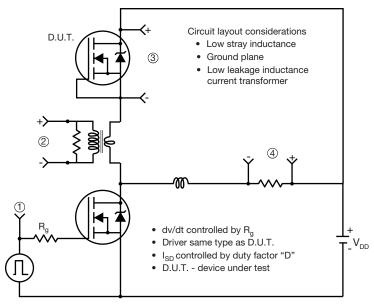


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dv/dt Test Circuit



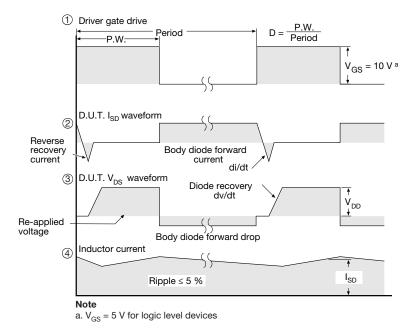
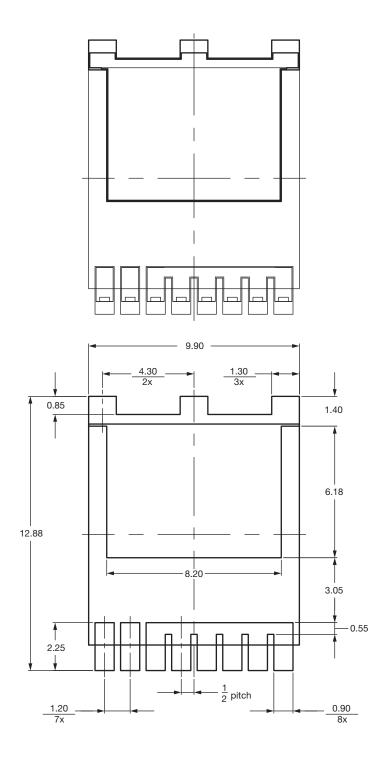


Fig. 19 - For N-Channel

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?92424.



Recommended Land Pattern PowerPAK® 10 x 12 (TOLL) (High Voltage)



Note

• Dimensions in mm

ECN: S22-1061-Rev. C, 26-Dec-2022

DWG: 3013



Legal Disclaimer Notice

Vishay

Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Hyperlinks included in this datasheet may direct users to third-party websites. These links are provided as a convenience and for informational purposes only. Inclusion of these hyperlinks does not constitute an endorsement or an approval by Vishay of any of the products, services or opinions of the corporation, organization or individual associated with the third-party website. Vishay disclaims any and all liability and bears no responsibility for the accuracy, legality or content of the third-party website or for that of subsequent links.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.